

#6/Response
4/23/03

Kim et al. 09/992,389

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of KIM et al.

Serial No.: 10/001,314

Filed: November 14, 2001

) METHOD FOR FORMING ISOLATION
) LAYER OF SEMICONDUCTOR DEVICE
)
) Attorney Docket: TJK/204
)
) Group Art Unit: 2823
)
) Examiner: N. Berezny
)

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on 4/14, 2003.

D. S. Rupert

Douglas S. Rupert

Attorney for Applicants

Reg. No. 44,434

Date of Signature: 4/14, 2003

Assistant Commissioner for Patents

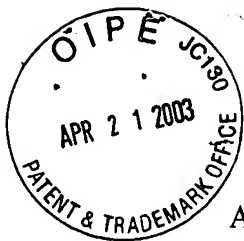
Washington, D.C. 20231

RESPONSE TO OFFICE ACTION

Dear Sir:

This paper is filed in response to the Office Action mailed January 14, 2003 in connection with the above-designated application.

RECEIVED
APR 22 2003
TECHNOLOGY CENTER 2800



2823

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANTS: Kim et al. EXAMINER: N. Berezny
SERIAL NO.: 10/001,314 GROUP: 2823
FILED: 11/14/2001 CASE NO.: TJK/204
TITLE: METHOD FOR FORMING ISOLATION LAYER OF SEMICONDUCTOR DEVICE

TECHNOLOGY CENTER 2800

APR 22 2003

RECEIVED

AMENDMENT TRANSMITTAL LETTER

Box Non-Fee Amendment
Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Please find enclosed the following documents pertaining to the above referenced application:

1. Response to Office Action (3 pages)
2. Return Receipt Postcard

There is no fee due for the filing of this amendment. In the event of non-payment or improper payment of a required fee, the Commissioner is hereby authorized to charge or credit additional fees to **Deposit Account No. 23-2126**. A duplicate copy of this letter is enclosed for fee purposes.

CERTIFICATE OF MAILING

Respectfully submitted,

DSL DT
Douglas S. Rupert
Registration No. 44,434

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as first class mail in an envelope addressed to Assistant Commissioner for Patents, Washington, D.C. 20231, on April 14, 2003.

Signature

Date

Mindy Fitch 4/14/03